

# VFE asic considerations



## Saclay's Upgrade Workshop

**Marc Dejardin**  
**CEA-Saclay Irfu/SPP**

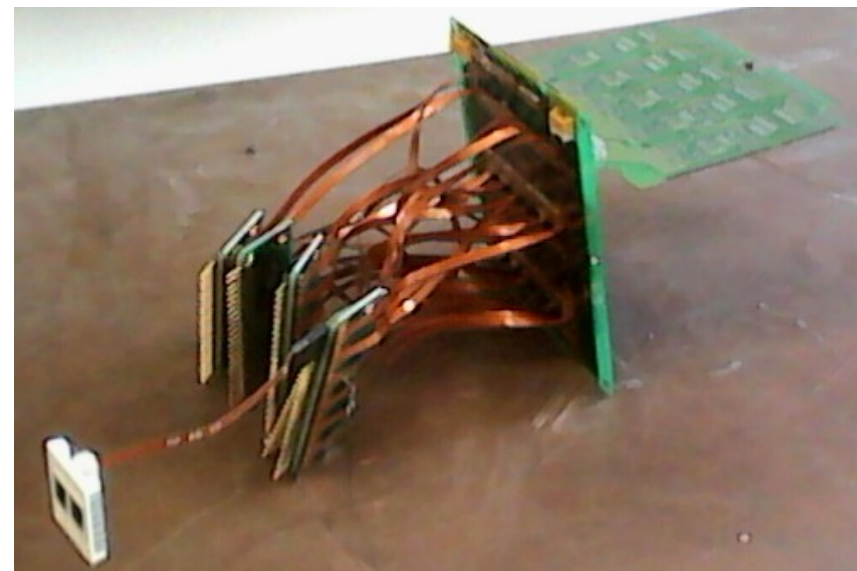


## Reminder

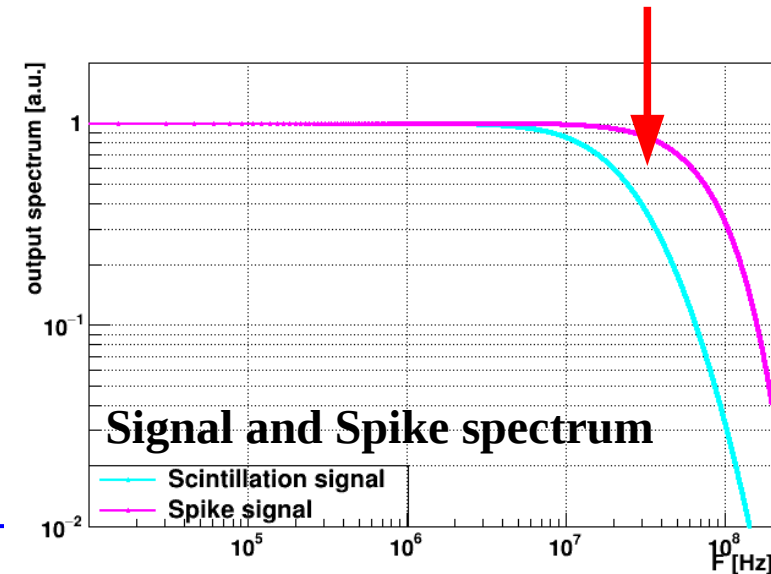


- **For HL-LHC upgrades**
  - **Keep energy measurement as good as possible**
  - **Improve spike tagging**
  - **Mitigate APD leakage current increase**
  - **Mitigate OOT pileup**
  - **Mitigate IT pileup**
- **Guidelines**
  - **Get shaping time as short as possible**
    - ▶ **OOT pileup, leakage current induced noise**
  - **Get amplification chain BW as high as possible**
    - ▶ **Increase signal information**
      - **Spike tagging, timing information**

- **Mother board kaptons (d = 130 mm)**
  - $R_{MB} = 53 \text{ m}\Omega/\text{cm}$
  - $L_{MB} = 4.5 \text{ nH/cm}$
  - $C_{MB} = 2.4 \text{ pF/cm}$
- **APD capsule kaptons (d from 70 to 165 mm)**
  - $R_{APD} = 35 \text{ m}\Omega/\text{cm}$
  - $L_{APD} = 2.4 \text{ nH/cm}$
  - $C_{APD} = 1.7 \text{ pF/cm}$
- **LC resonator with APD capacitance (160 pF)**
  - Resonance frequency  $\sim 40 \text{ MHz}$
  - Electronic Bandwidth upper limit
- **Ultimate performances limited by the system**



The discriminating information is there



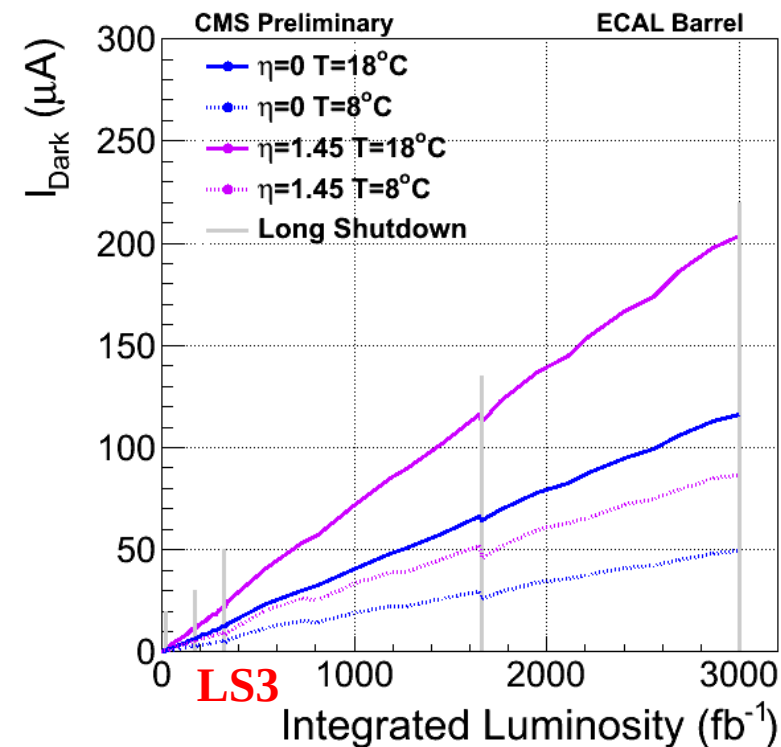
- **APD: reverse biased diode**
  - **Current source**
  - **Signal: photon induced variation of reverse current**
  - **Noise: random variation of reverse current =  $f(I_{\text{leak}})$** 
    - ▶  $\tilde{i}_{\text{APD}} = 5.4 \sqrt{I_{\text{leak}}} \text{ [pA}/\sqrt{\text{Hz}}]$  ( $I_{\text{leak}}$  in  $\mu\text{A}$ ,  $M=50$ ,  $F=2$ )
    - ▶ **Equivalent of noise generated by  $R_{\text{eq}} = 525/I_{\text{leak}} \Omega$**
  - **Bandwidth: unknown but large**
    - ▶ **Well above connection cutoff frequency**
  - **Capacitance:  $\sim 160 \text{ pF}$**
  - **Connection line (kapton):**
    - ▶  $C_{\text{kapton}} = 40\text{-}60 \text{ pF}$  from M1 to M4
    - ▶  $L_{\text{kapton}} = 75\text{-}100 \text{ nH}$  from M1 to M4



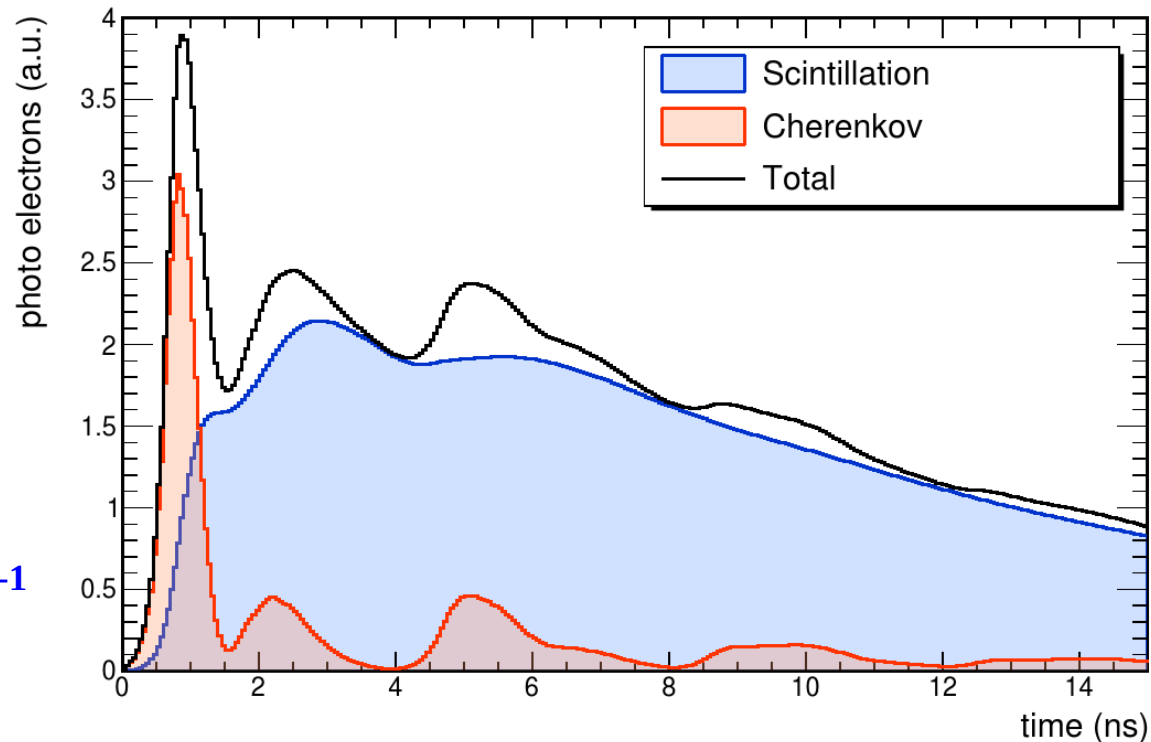
# Leakage current



- **HL\_LHC start (300 fb<sup>-1</sup>):**
  - 10-20  $\mu\text{A}$  (18°C)      5-10  $\mu\text{A}$  (8°C)
- **HL\_LHC end (3000 fb<sup>-1</sup>):**
  - 100-200  $\mu\text{A}$  (18°C)      50-110  $\mu\text{A}$  (8°C)
- **VFE should be efficient for all scenarios**
  - **First year of HL-LHC perhaps not at full lumi...**

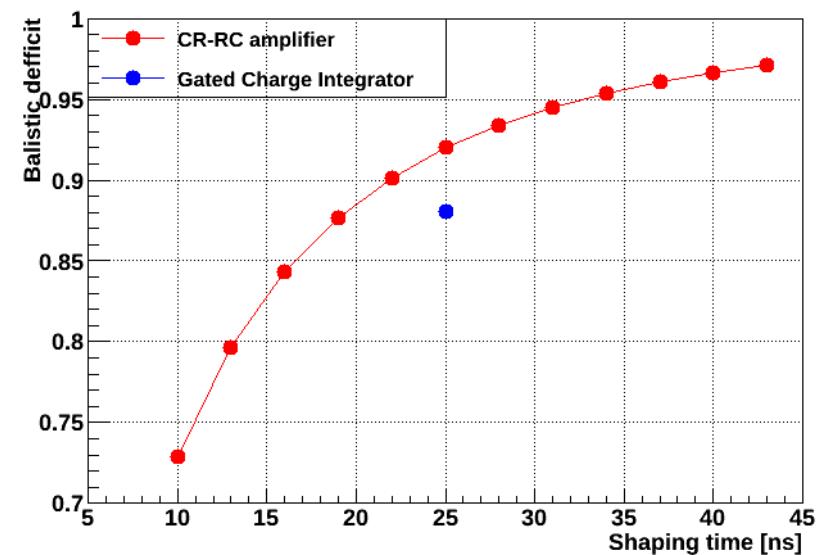
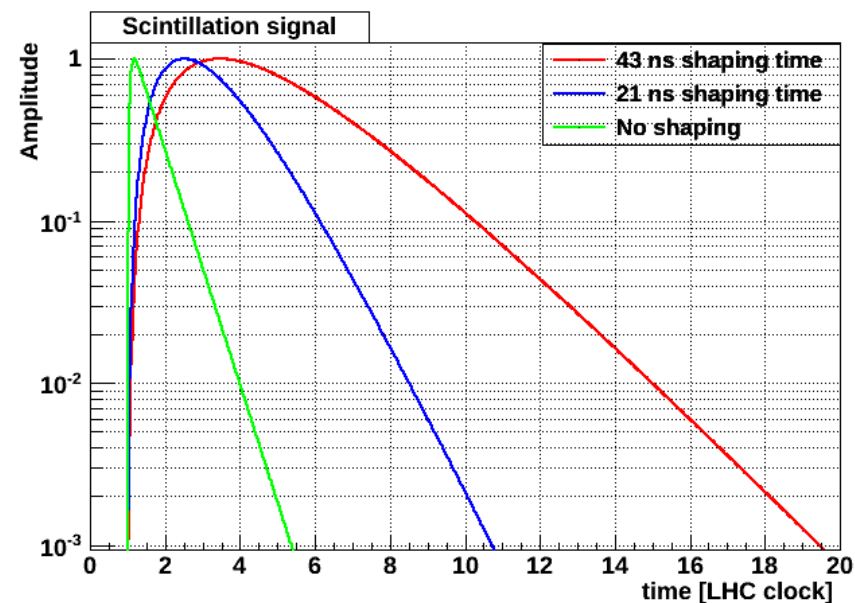


- **Spike: Dirac energy deposition in APD core**
  - ~ isolated crystal
  - In time and out-of-time wrt LHC collisions
- **Scintillation: Follows photon arrival on APD**
  - 4.5 p.e./MeV w.o. loss
  - 3.5 p.e./MeV @ 300 fb<sup>-1</sup>
  - 2.8 p.e./MeV @ 3000 fb<sup>-1</sup>
  - +30 % @ 8°C !
- **Shape analysis to discriminate**
  - On analog signal
  - On sampled signal



- **Dynamics:**
  - From APD induced noise (100 MeV ?)
  - Up to 2 TeV
    - ▶ 14.3 bits
- **Number of gains**
  - Depends on ADC choice
  - 2 gains (x10, x1) seems enough (with 12 bits ADC)
- **Linearity**
  - No real constraint but present MGPA is quite good
    - ▶ Could be taken as reference:  $\pm 0.1\%$
- **Shape stability (with time, with amplitude)**
  - Should be good enough for
    - ▶ Multifit performances and timing measurements
    - ▶ To be quantified

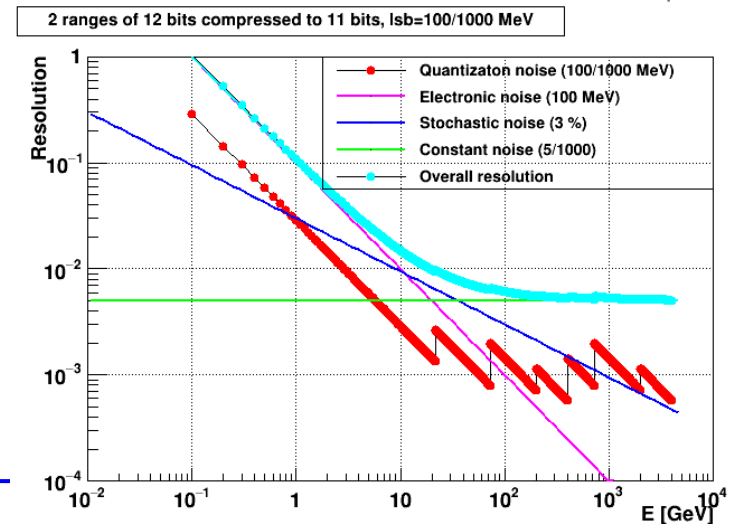
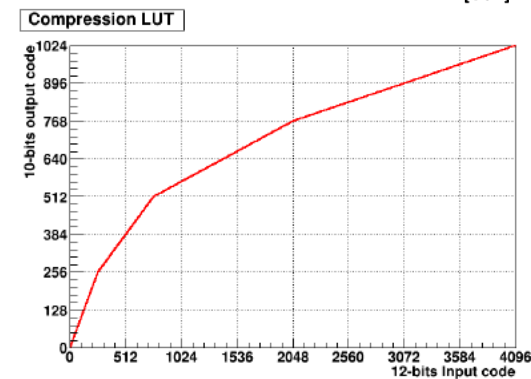
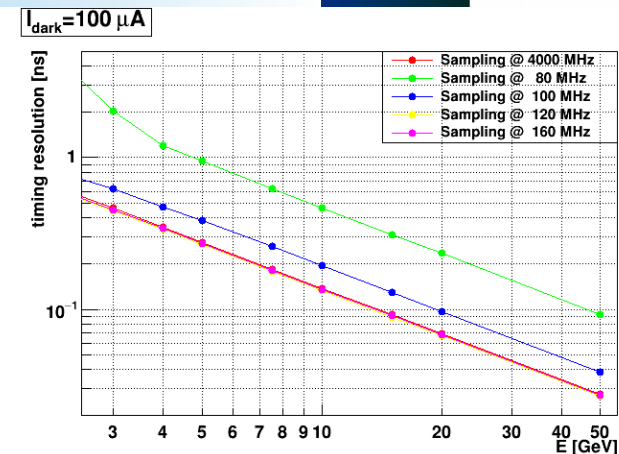
- **Shorter**
  - **Less OOT contamination**
  - **Less integration of leakage current fluctuations**
    - ▶ **Less noise**
  
- **But less integration of signal charge**
  - ▶ **Less mV/fC**
  - ▶ **Not relevant for TIA**





- **MGPA++ : MGPA evolution**
  - New technology
  - Reduce shaping time
  - Extra features (spike tagging)
- **TIA**
  - Image of APD current, BW limited (~35 MHz)
  - TSMC 130nm technology
  - Extra features done in OD (spike tagging, TDC, filtering)
- **QIE++ : QIE evolution**
  - Gated charge integrator, gate width to be defined
  - Bi-cmos technology
  - Enhanced ADC wrt QIE13
  - Extra features (tdc)

- **With shorter shaping**
  - **Oversampling mandatory**
    - ▶ For OOT pileup mitigation (multifit over-constraining)
    - ▶ For shape analysis (spike tagging)
    - ▶ For IT pileup mitigation (timing)
    - ▶ 80, 160 MHz ?
  - **Drawback : More data to transmit**
- **Digitization noise should be negligible wrt other contributions**
- **Should include extra feature for versatility**
  - **Output look-up table for compression**
  - **Gain switching behavior**
  - **Sampling phase tuning**
- **Architecture à-la ADC41240 has proven its robustness**
  - **Could be taken as baseline design**



- **Define case studies for comparison**
  - @ 300 fb<sup>-1</sup>, 1000 fb<sup>-1</sup>, 3000 fb<sup>-1</sup> and 5000 fb<sup>-1</sup>
  - With 0, 100, 200 PU
- **Electronics performances**
  - Noise
  - Spike tagging efficiency
  - Timing resolution
  - Data volume
  - Development risk
- **Physics performances ?**
  - Hgg with PU
  - gg vertexing
  - X(750)gg
- **Options**
  - Sampling rate
- **Inputs and tools**
  - Shapes and PU from toyMC (tuned with TB results)
  - APD noise model from measurements
  - Electronic noise from simulation



# Conclusion



- Still lot of questions and options
- Let's hear more details on various options

15:00	<b>TIA</b> <i>112, CEA-Saclay INSTN</i>	<i>Pascal Baron</i> 15:00 - 15:40
	<b>ADC requirements and plans</b> <i>112, CEA-Saclay INSTN</i>	<i>Joao Varela</i> 15:40 - 16:20
16:00	<b>Coffee/discussion</b> <i>112, CEA-Saclay INSTN</i>	16:20 - 16:50
17:00	<b>QIE</b> <i>112, CEA-Saclay INSTN</i>	<i>Jim Hirschauer</i> 16:50 - 17:30
	<b>Discussion</b> <i>112, CEA-Saclay INSTN</i>	17:30 - 18:00
18:00		
09:00	<b>MPGA++</b> <i>112, CEA-Saclay INSTN</i>	<i>Stephen Thomas</i> 09:00 - 09:40